

Chip Bead For EMI Suppression

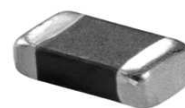
CIB/CIM31 Series (3216/ EIA 1206)

APPLICATION

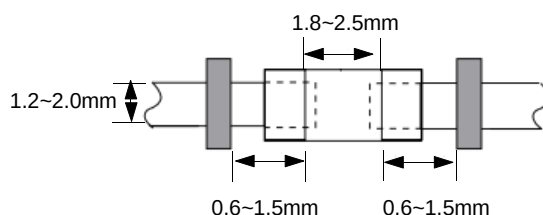
High frequency EMI prevention application to computers, printers, VCRs, TVs and mobile phones.

FEATURES

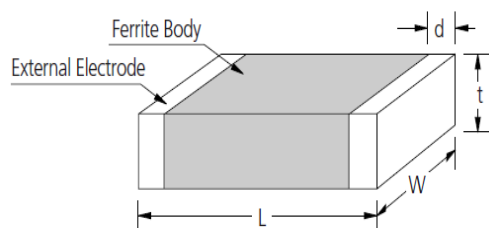
- Perfect shape for automatic mounting, with no directionality.
- Excellent solderability and high heat resistance for either flow or reflow soldering
- Monolithic inorganic material construction for high reliability
- Closed magnetic circuit configuration avoids crosstalk and is suitable for high density PCBs.



RECOMMENDED LAND PATTERN



DIMENSION



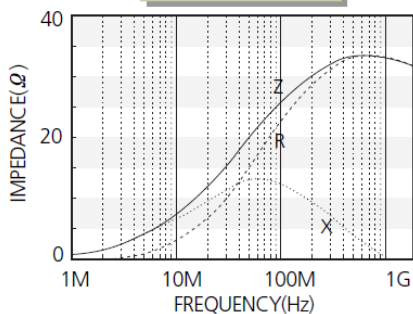
Type	Dimension [mm]			
	L	W	t	d
31	3.2±0.2	1.6±0.2	1.1±0.2	0.5+0.2 -0.3

DESCRIPTION

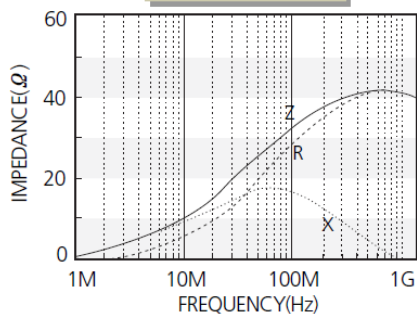
Part no.	Thickness (mm)	Impedance (Ω)±25%@100MHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIB31P260	1.1±0.2	26	0.05	2000
CIB31P310	1.1±0.2	31	0.05	2000
CIB31P500	1.1±0.2	50	0.05	2000
CIB31P600	1.1±0.2	60	0.05	1500
CIB31P700	1.1±0.2	70	0.10	1500
CIM31U101	1.1±0.2	100	0.15	500
CIM31U601	1.1±0.2	600	0.30	400
CIM31J151	1.1±0.2	150	0.20	600
CIM31J221	1.1±0.2	220	0.20	600
CIM31J301	1.1±0.2	300	0.25	600
CIM31J601	1.1±0.2	600	0.30	600
CIM31J801	1.1±0.2	800	0.40	500
CIM31J102	1.1±0.2	1000	0.45	500
CIM31J152	1.1±0.2	1500(at 70MHz)	0.55	300

CHARACTERISTIC DATA

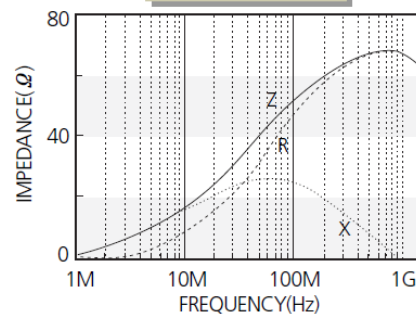
CIB31P260



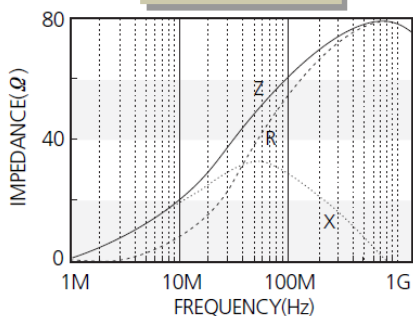
CIB31P310



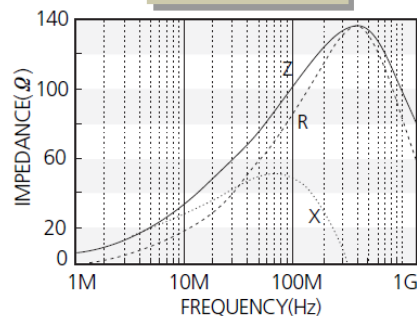
CIB31P500



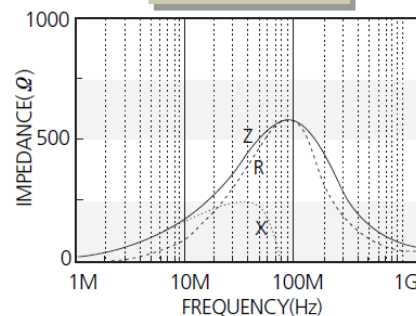
CIB31P700



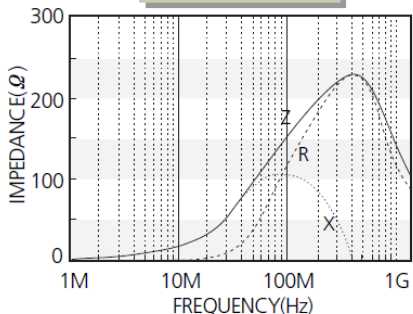
CIM31U101



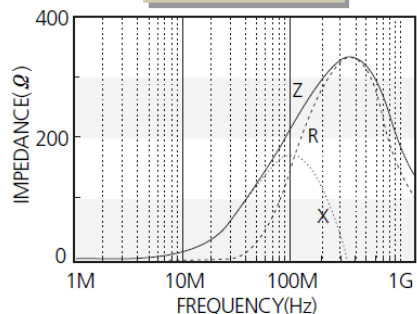
CIM31U601



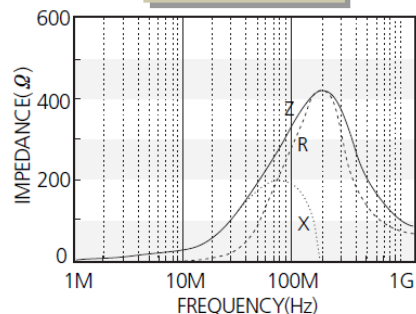
CIM31J151



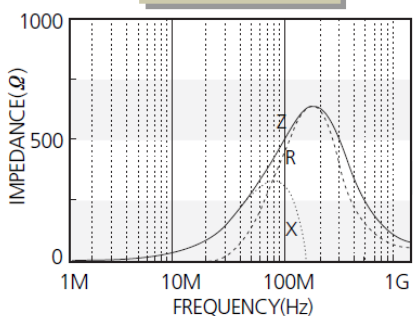
CIM31J221



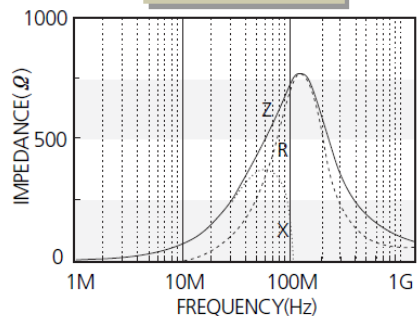
CIM31J301



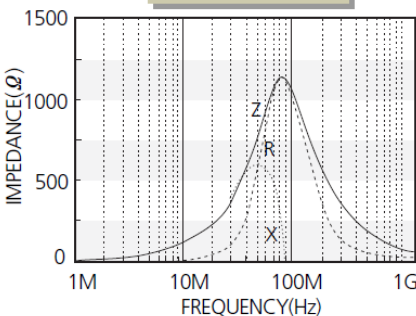
CIM31J601



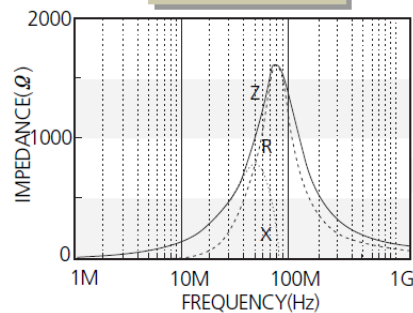
CIM31J801



CIM31J102



CIM31J152



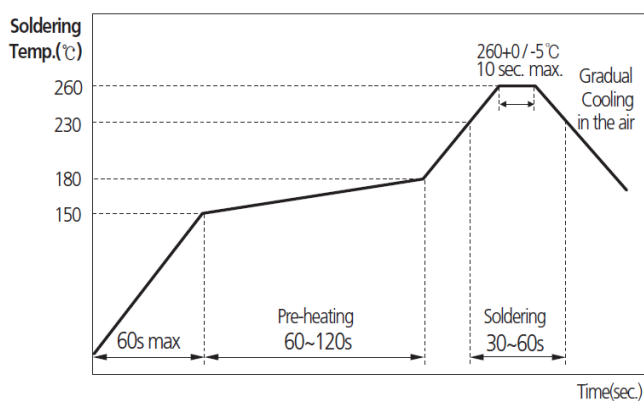
PRODUCT IDENTIFICATION

CI	M	31	J	221	N	E
(1)	(2)	(3)	(4)	(5)	(6)	(7)

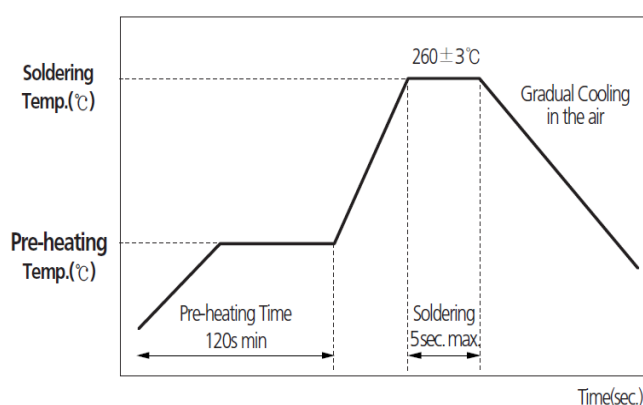
- (1) Chip Beads
 (2) M: Multi-layer type B:Mono-layer type
 (3) Dimension
 (4) Material Code
 (5) Nominal impedance (700:70Ω, 221:220Ω)
 (6) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
 (7) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Card Board Taping	3,000

■ NOTICE :All specifications are subject to change without previous notice. Please contact with product representatives or engineers to check specifications.